

NB6L611

2.5V / 3.3V 1:2 Differential LVPECL Clock / Data Fanout Buffer

Multi-Level Inputs with Internal Termination

Description

The NB6L611 is a differential 1:2 clock or data fanout buffer. The differential inputs incorporate internal $50\ \Omega$ termination resistors that are accessed through the VTD pins and will accept LVPECL, CML, LVDS, LVCMOS or LVTTL logic levels.

The V_{REFAC} reference output can be used to rebias capacitor-coupled differential or single-ended input signals. When used, decouple V_{REFAC} with a $0.01\ \mu F$ capacitor and limit current sourcing or sinking to $0.5\ mA$. When used, decouple V_{REFAC} with a $0.01\ \mu F$ capacitor and limit current sourcing or sinking to $0.5\ mA$. When not used, V_{REFAC} output should be left open.

The device is housed in a small $3\times 3\ mm$ 16 pin QFN package.

The NB6L611 is a member of the ECLinPS MAX™ family of high performance clock and data management products.

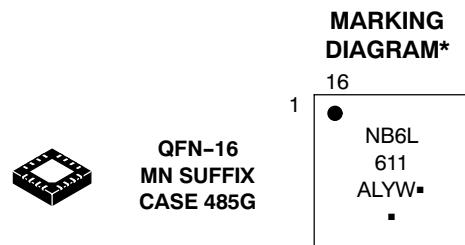
Features

- Input Clock Frequency > 4.0 GHz
- 280 ps Typical Propagation Delay
- 100 ps Typical Rise and Fall Times
- 0.5 ps maximum RMS Clock Jitter
- Differential LVPECL Outputs, 780 mV Amplitude, typical
- LVPECL Operating Range: V_{CC} = 2.375 V to 3.63 V with V_{EE} = 0 V
- NECL Operating Range: V_{CC} = 0 V with V_{EE} = -2.375 V to -3.63 V
- Internal Input Termination Resistors, $50\ \Omega$
- V_{REFAC} Reference Output Voltage
- Functionally Compatible with Existing 2.5 V / 3.3 V LVEL, LVEP, EP, and SG Devices
- -40°C to +85°C Ambient Operating Temperature
- These are Pb-Free Devices



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A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
■ = Pb-Free Package
(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

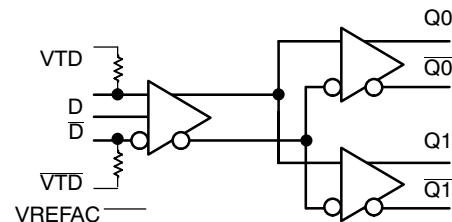


Figure 1. Simplified Logic Diagram

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.

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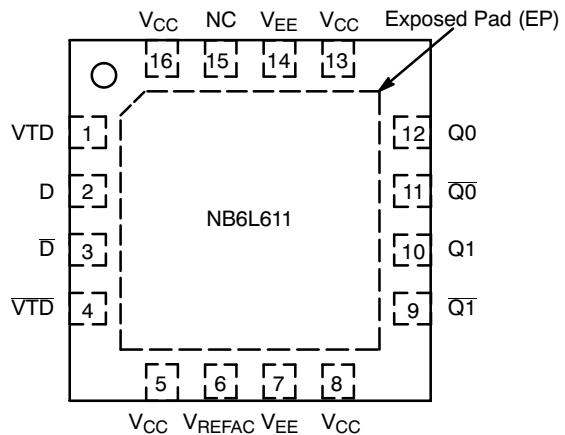


Figure 2. Pin Configuration (Top View)

Table 1. PIN DESCRIPTION

Pin	Name	I/O	Description
1	VTD	-	Internal 50 Ω Termination Pin for D input.
2	D	ECL, CML, LVCMS, LVDS, LVTT Input	Noninverted Differential Input. Note1. Internal 50 Ω Resistor to Termination Pin, VTD.
3	D-bar	ECL, CML, LVCMS, LVDS, LVTT Input	Inverted Differential Input. Note 1. Internal 50 Ω Resistor to Termination Pin, VTD.
4	VTD-bar	-	Internal 50 Ω Termination Pin for D-bar input.
5	V _{CC}	-	Positive Supply Voltage
6	V _{REFAC}		Output Reference Voltage for direct or capacitor coupled inputs
7	V _{EE}	-	Negative Supply Voltage
8	V _{CC}	-	Positive Supply Voltage
9	Q-bar1	LVPECL Output	Inverted Differential Output. Typically Terminated with 50 Ω Resistor to V _{CC} - 2.0 V.
10	Q1	LVPECL Output	Noninverted Differential Output. Typically Terminated with 50 Ω Resistor to V _{CC} - 2.0 V.
11	Q-bar0	LVPECL Output	Inverted Differential Output. Typically Terminated with 50 Ω Resistor to V _{CC} - 2.0 V.
12	Q0	LVPECL Output	Noninverted Differential Output. Typically Terminated with 50 Ω Resistor to V _{CC} - 2.0 V.
13	V _{CC}	-	Positive Supply Voltage
14	V _{EE}	-	Negative Supply Voltage
15	NC	-	No Connect
16	V _{CC}	-	Positive Supply Voltage
-	EP	-	The Exposed Pad (EP) on the QFN-16 package bottom is thermally connected to the die for improved heat transfer out of package. The exposed pad must be attached to a heat-sinking conduit. The pad is not electrically connected to the die, but is recommended to be electrically and thermally connected to V _{EE} on the PC board.

1. In the differential configuration when the input termination pins (VTD, VTD-bar) are connected to a common termination voltage or left open, and if no signal is applied on D/D-bar input, then, the device will be susceptible to self-oscillation.
2. All V_{CC} and V_{EE} pins must be externally connected to a power supply for proper operation.

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Table 2. ATTRIBUTES

Characteristics		Value
ESD Protection	Human Body Model Machine Model	> 2 kV > 200V
Moisture Sensitivity	16-QFN	Level 1
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in
Transistor Count		
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test		

For additional information, see Application Note AND8003/D.

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V_{CC}	Positive Power Supply	$V_{EE} = 0 \text{ V}$		4.0	V
V_{EE}	Negative Power Supply	$V_{CC} = 0 \text{ V}$		-4.0	V
V_{IO}	Positive Input/Output Voltage Negative Input/Output Voltage	$V_{EE} = 0 \text{ V}$ $V_{CC} = 0 \text{ V}$	$-0.5 \leq V_{IO} \leq V_{CC} + 0.5$ $+0.5 \geq V_{IO} \geq V_{EE} - 0.5$	4.5 -4.5	V V
V_{INPP}	Differential Input Voltage $ D - \bar{D} $			$V_{CC} - V_{EE}$	V
I_{IN}	Input Current Through R_T (50 Ω Resistor)	Static Surge		45 80	mA mA
I_{OUT}	Output Current (LVPECL Output)	Continuous Surge		50 100	mA mA
I_{VREFAC}	V_{REFAC} Sink/Source Current			± 2.0	mA
T_A	Operating Temperature Range	16 QFN		-40 to +85	°C
T_{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient) (Note 3)	0 lfpm 500 lfpm	QFN-16 QFN-16	42 35	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	(Note 3)	QFN-16	4	°C/W
T_{sol}	Wave Solder Pb-Free			265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

3. JEDEC standard multilayer board – 2S2P (2 signal, 2 power) with 8 filled thermal vias under exposed pad.

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Table 4. DC CHARACTERISTICS, Multi-Level Inputs $V_{CC} = 2.375\text{ V}$ to 3.63 V , $V_{EE} = 0\text{ V}$, or $V_{CC} = 0\text{ V}$, $V_{EE} = -2.375\text{ V}$ to -3.63 V , $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$

Symbol	Characteristic	Min	Typ	Max	Unit
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POWER SUPPLY CURRENT

I_{CC}	Power Supply Current (Inputs and Outputs Open)	30	45	60	mA
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LVPECL OUTPUTS (Notes 4 and 5)

V_{OH}	Output HIGH Voltage $V_{CC} = 3.3\text{ V}$ $V_{CC} = 2.5\text{ V}$	$V_{CC} - 1075$ 2225 1425	$V_{CC} - 950$ 2350 1550	$V_{CC} - 825$ 2475 1675	mV
V_{OL}	Output LOW Voltage $V_{CC} = 3.3\text{ V}$ $V_{CC} = 2.5\text{ V}$	$V_{CC} - 1875$ 1475 675	$V_{CC} - 1725$ 1575 775	$V_{CC} - 1625$ 1675 875	mV

DIFFERENTIAL INPUT DRIVEN SINGLE-ENDED (see Figures 5 and 6) (Note 6)

V_{th}	Input Threshold Reference Voltage Range (Note 7)	$V_{EE} + 1050$		$V_{CC} - 150$	mV
V_{IH}	Single-ended Input HIGH Voltage	$V_{th} + 150$		V_{CC}	mV
V_{IL}	Single-ended Input LOW Voltage	V_{EE}		$V_{th} - 150$	mV
V_{ISE}	Single-ended Input Voltage Amplitude ($V_{IH} - V_{IL}$)	300		$V_{CC} - V_{EE}$	mV

V_{REFAC}

V_{REFAC}	Output Reference Voltage ($V_{CC} \geq 25\text{ V}$)	$V_{CC} - 1.525$	$V_{CC} - 1.425$	$V_{CC} - 1.325$	mV
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DIFFERENTIAL INPUTS DRIVEN DIFFERENTIALLY (see Figures 7, 8 and 9) (Note 8)

V_{IHD}	Differential Input HIGH Voltage	$V_{EE} + 1200$		V_{CC}	mV
V_{ILD}	Differential Input LOW Voltage	V_{EE}		$V_{CC} - 150$	mV
V_{ID}	Differential Input Voltage ($V_{IHD} - V_{ILD}$)	$V_{EE} + 150$		$V_{CC} - V_{EE}$	mV
V_{CMR}	Input Common Mode Range (Differential Configuration) (Note 9)	$V_{EE} + 950$		$V_{CC} - 75$	mV
I_{IH}	Input HIGH Current D/D, (VTD/VTD Open)	-150		150	μA
I_{IL}	Input LOW Current D/D, (VTD/VTD Open)	-150		150	μA

TERMINATION RESISTORS

R_{TIN}	Internal Input Termination Resistor (Measured from D to VTD)	40	50	60	Ω
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NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm . Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

4. LVPECL outputs loaded with $50\text{ }\Omega$ to $V_{CC} - 2.0\text{ V}$ for proper operation.
5. Input and output parameters vary 1:1 with V_{CC} .
6. V_{th} , V_{IH} , V_{IL} , and V_{ISE} parameters must be complied with simultaneously.
7. V_{th} is applied to the complementary input when operating in single-ended mode.
8. V_{IHD} , V_{ILD} , V_{ID} and V_{CMR} parameters must be complied with simultaneously.
9. V_{CMR} minimum varies 1:1 with V_{EE} , V_{CMR} maximum varies 1:1 with V_{CC} . The V_{CMR} range is referenced to the most positive side of the differential input signal.

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Table 5. AC CHARACTERISTICS $V_{CC} = 2.375\text{ V}$ to 3.63 V , $V_{EE} = 0\text{ V}$, or $V_{CC} = 0\text{ V}$, $V_{EE} = -2.375\text{ V}$ to -3.63 V ,
 $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$; (Note 10)

Symbol	Characteristic		Min	Typ	Max	Unit
V_{OUTPP}	Output Voltage Amplitude (@ V_{INPP}) (Note 14) (See Figure 3)	$f_{in} \leq 1.5\text{ GHz}$ $f_{in} = 2.0\text{ GHz}$ $f_{in} = 3.0\text{ GHz}$ $f_{in} = 4.0\text{ GHz}$	725 520 320 170	780 680 500 400		mV
t_{PD}	Propagation Delay	D to Q	225	280	375	ps
t_{SKew}	Duty Cycle Skew (Note 11) Within Device Skew Device to Device Skew (Note 12)			3	15 15 80	ps
t_{DC}	Output Clock Duty Cycle (Reference Duty Cycle = 50%)	$f_{in} \leq 4.0\text{ GHz}$	40	50	60	ps
t_{JITTER}	RMS Random Clock Jitter (Note 13)	$f_{in} \leq 4.0\text{ GHz}$		0.2	0.5	ps
V_{INPP}	Input Voltage Swing/Sensitivity (Differential Configuration) (Note 14)		150		$V_{CC} - V_{EE}$	mV
t_r, t_f	Output Rise/Fall Times @ 0.5 GHz (20% – 80%)	Q, \bar{Q}		100	170	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

10. Measured by forcing V_{INPP} (MIN) from a 50% duty cycle clock source. All loading with an external $R_L = 50\Omega$ to $V_{CC} = 2.0\text{ V}$. Input edge rates 40 ps (20% – 80%).

11. Duty cycle skew is measured between differential outputs using the deviations of the sum of T_{pw-} and T_{pw+} @ 0.5GHz.

12. Device to device skew is measured between outputs under identical transition @ 0.5 GHz.

13. Additive RMS jitter with 50% duty cycle clock signal.

14. Input and output voltage swing is a single-ended measurement operating in differential mode.

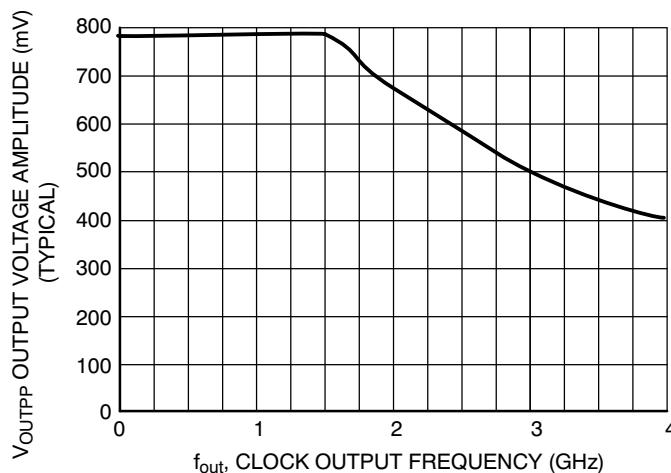


Figure 3. Output Voltage Amplitude (V_{OUTPP}) versus Output Frequency at Ambient Temperature (Typical)

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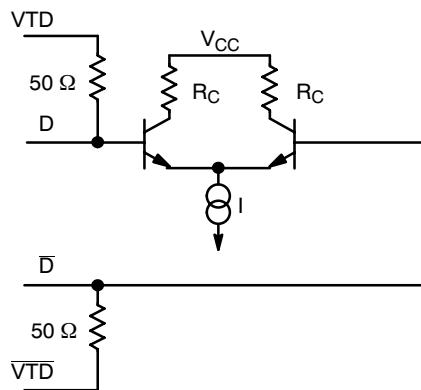


Figure 4. Input Structure

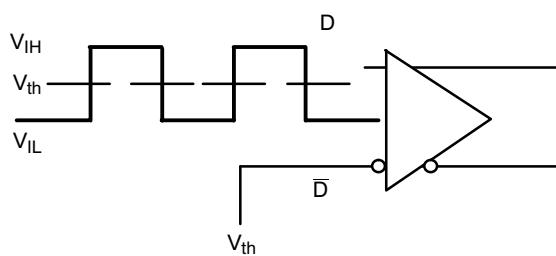


Figure 5. Differential Input Driven Single-Ended

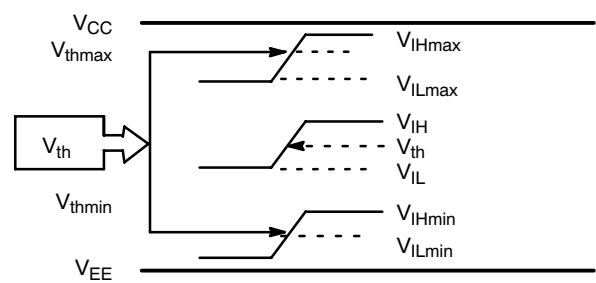


Figure 6. V_{th} Diagram

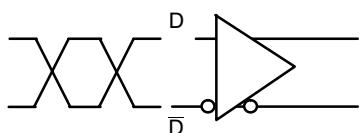


Figure 7. Differential Inputs Driven Differentially

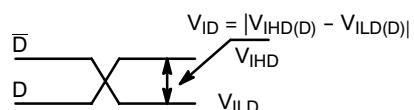


Figure 8. Differential Inputs Driven Differentially

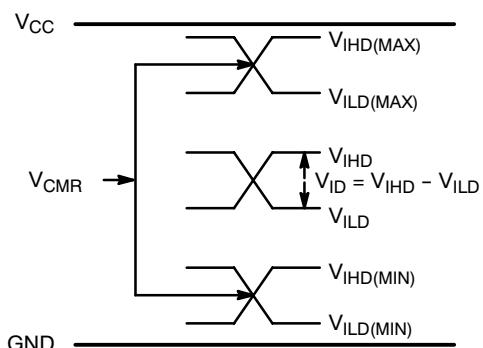


Figure 9. V_{CMR} Diagram

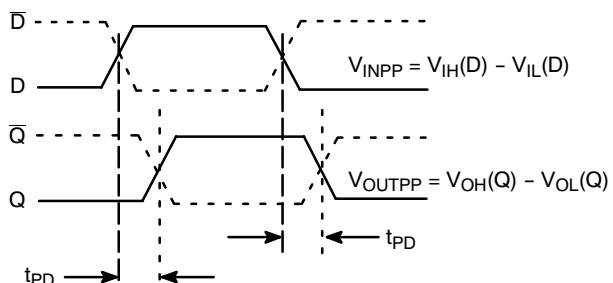


Figure 10. AC Reference Measurement

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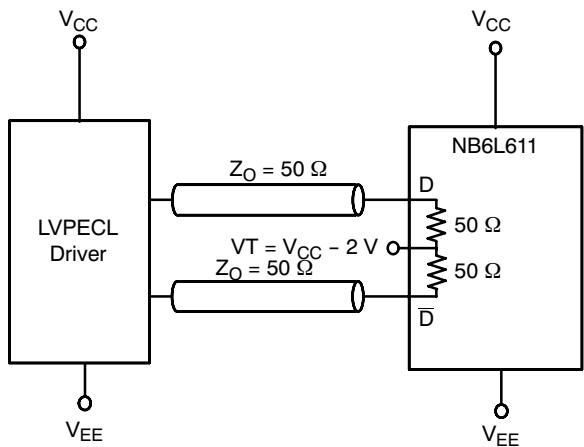


Figure 11. LVPECL Interface

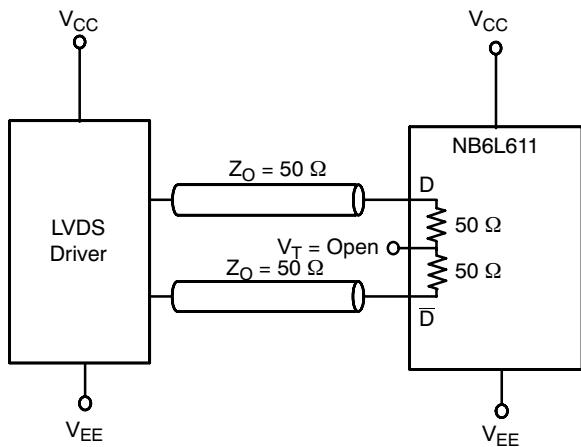


Figure 12. LVDS Interface

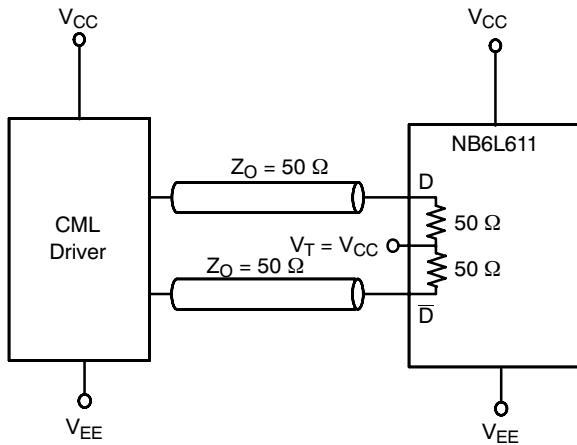


Figure 13. Standard 50Ω Load CML Interface

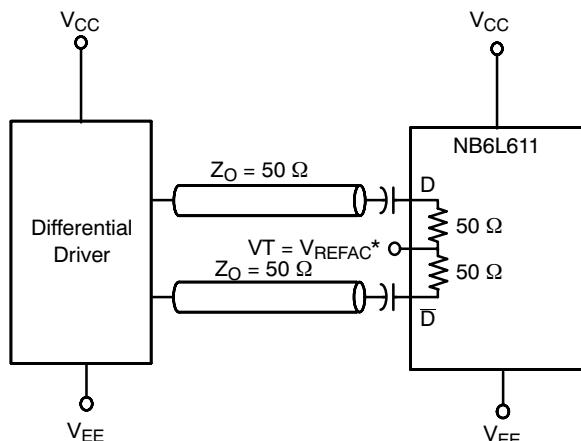


Figure 14. Capacitor-Coupled Differential Interface
(V_T Connected to V_{REFAC})

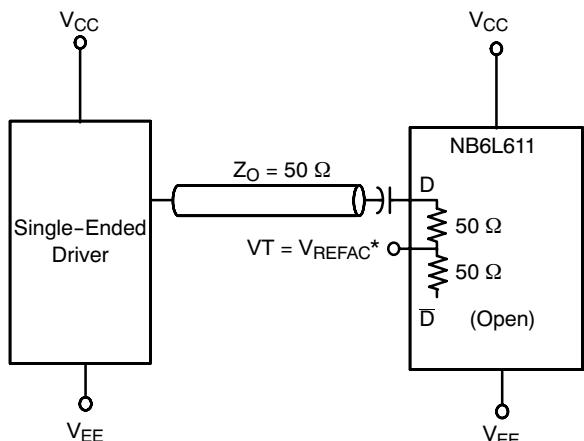
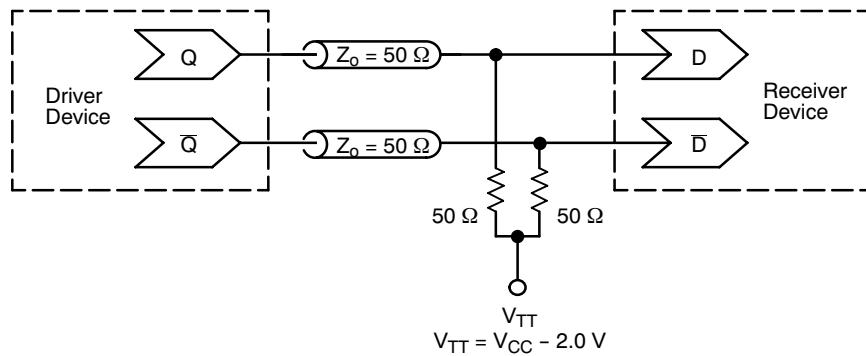


Figure 15. Capacitor-Coupled Single-Ended Interface
(V_T Connected to V_{REFAC})

* V_{REFAC} bypassed to ground with a $0.01 \mu F$ capacitor

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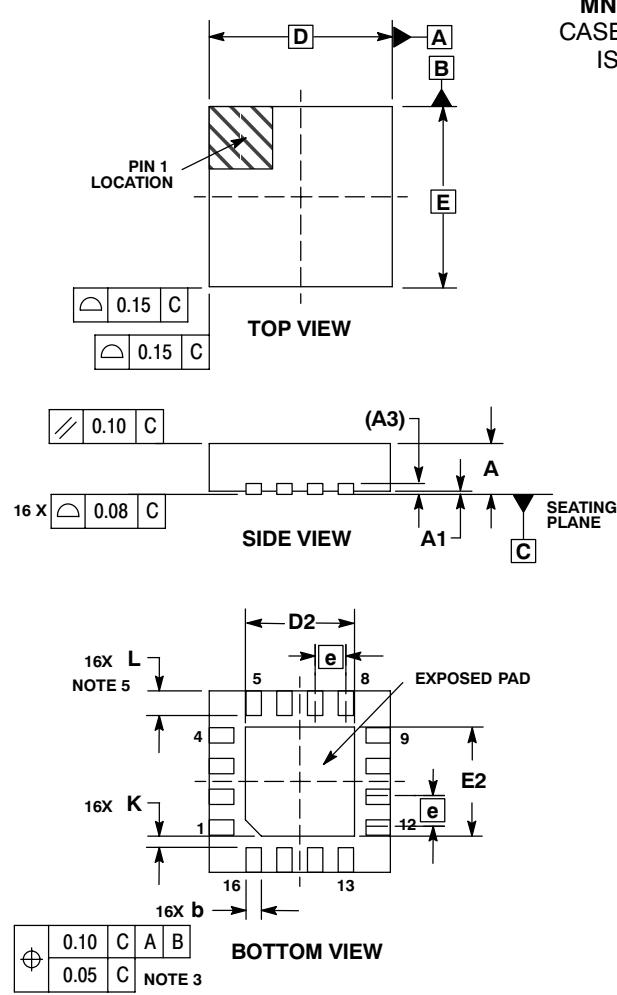
**Figure 16. Typical Termination for Output Driver and Device Evaluation
(See Application Note AND8020/D – Termination of ECL Logic Devices.)**

ORDERING INFORMATION

Device	Package	Shipping [†]
NB6L611MNG	QFN-16 (Pb-free)	123 Units / Rail
NB6L611MNR2G	QFN-16 (Pb-free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS



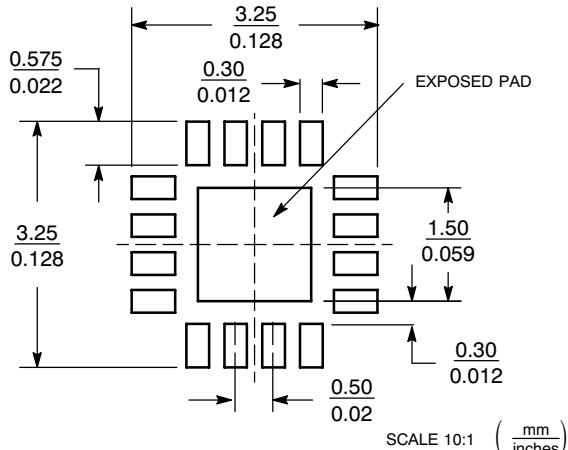
**16 PIN QFN
MN SUFFIX
CASE 485G-01
ISSUE C**

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. L_{max} CONDITION CAN NOT VIOLATE 0.2 MM MINIMUM SPACING BETWEEN LEAD TIP AND FLAG

DIM	MILLIMETERS	
	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20 REF	
b	0.18	0.30
D	3.00 BSC	
D2	1.65	1.85
E	3.00 BSC	
E2	1.65	1.85
e	0.50 BSC	
K	0.18 TYP	
L	0.30	0.50

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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